

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

BIB DATA SHEET

CONFIRMATION NO. 4972

## ## ## ## ## ## ## ## ## ## ## ## ##	SERIAL NUM	UMBER FILING or 37		I(c)	CLASS		GROUP ART UNIT		ATTORNEY DOCKET		
APPLICANTS Jiro Matsumoto, Tokyo, JAPAN; ******CONTINUING DATA***********************************	10/727,662				257		2814				
Jiro Matsumoto, Tokyo, JAPAN; ***********************************	RULE										
This application is a DIV of 10/103,889 03/25/2002 PAT 6,682,958 **FOREIGN APPLICATIONS ************************************											
JAPAN 2001-089851 03/27/2001 *** IF REQUIRED, FOREIGN FILING LICENSE GRANTED **	** CONTINUING DATA ***********************************										
Foreign Priority claimed	** FOREIGN APPLICATIONS ************************************										
ADDRESS JUNICHI MIMURA OKI AMERICA INC. 1101 14TH STREET, N.W. SUITE 555 WASHINGTON, DC 20005 UNITED STATES TITLE Sealing apparatus for semiconductor wafer, mold of sealing apparatus, and semiconductor wafer FILING FEE RECEIVED 1990 FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT No for following: Met after Allowance LP	** IF REQUIRED, FOREIGN FILING LICENSE GRANTED ** 01/24/2004										
ADDRESS JUNICHI MIMURA OKI AMERICA INC. 1101 14TH STREET, N.W. SUITE 555 WASHINGTON, DC 20005 UNITED STATES TITLE Sealing apparatus for semiconductor wafer, mold of sealing apparatus, and semiconductor wafer FILING FEE RECEIVED 1990 FEES: Authority has been given in Paper No	35 USC 119(a-d) conditions met ✓ Yes ☐ No ☐ Met after Allowance				COUNTR						
JUNICHI MIMURA OKI AMERICA INC. 1101 14TH STREET, N.W. SUITE 555 WASHINGTON, DC 20005 UNITED STATES TITLE Sealing apparatus for semiconductor wafer, mold of sealing apparatus, and semiconductor wafer FILING FEE RECEIVED 1990 FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT No for following: All Fees All Fees I.16 Fees (Filing) 1.17 Fees (Processing Ext. of time) 1.18 Fees (Issue) Other	Verified and /LONG PHAM/ LP Initials				JAPAN		14	56		5	
OKI AMERICA INC. 1101 14TH STREET, N.W. SUITE 555 WASHINGTON, DC 20005 UNITED STATES TITLE Sealing apparatus for semiconductor wafer, mold of sealing apparatus, and semiconductor wafer FILING FEE RECEIVED 1990 FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT No for following: All Fees 1.16 Fees (Filing) 1.17 Fees (Processing Ext. of time) 1.18 Fees (Issue) Other Other Other Other Other Other Other	ADDRESS										
Sealing apparatus for semiconductor wafer, mold of sealing apparatus, and semiconductor wafer All Fees All Fees 1.16 Fees (Filing) 1.17 Fees (Processing Ext. of time) No for following: Other Other Other	OKI AMERICA INC. 1101 14TH STREET, N.W. SUITE 555 WASHINGTON, DC 20005										
FILING FEE RECEIVED 1990 FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT No for following: All Fees 1.16 Fees (Filing) 1.17 Fees (Processing Ext. of time) 1.18 Fees (Issue) Other	TITLE										
FILING FEE RECEIVED 1990 FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT No for following: 1.16 Fees (Filing) 1.17 Fees (Processing Ext. of time) 1.18 Fees (Issue) Other	Sealing apparatus for semiconductor wafer, mold of sealing apparatus, and semiconductor wafer										
FILING FEE RECEIVED 1990 FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT No for following: 1.17 Fees (Processing Ext. of time) 1.18 Fees (Issue) Other							☐ All Fe	☐ All Fees			
RECEIVED 1990 No to charge/credit DEPOSIT ACCOUNT No to charge/credit DEPOSIT ACCOUNT Of for following: 1.17 Fees (Processing Ext. of time) 1.18 Fees (Issue) 1.18 Fee		☐ 1.16 Fees (Filing)									
1990 No for following: 1990 Other		, ,						☐ 1.17 Fees (Processing Ext. of time)			
								☐ 1.18 Fees (Issue)			
☐ Credit								☐ Other			
							☐ Cred	☐ Credit			